

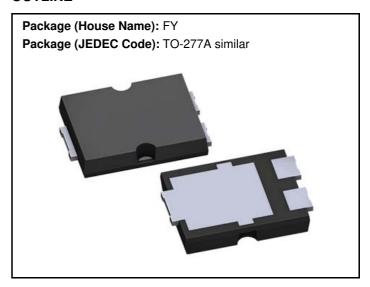
D10FY60VE

General Rectifying Diodes 600V, 10A

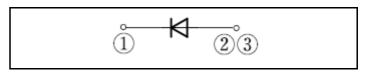
Feature

- Permit high current with a small package
- Based on AEC-Q101
- Halogen free
- · Pb free terminal
- RoHS:Yes

OUTLINE



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-55 to 150	°C
Junction temperature	Tj		-55 to 150	°C
Repetitive peak reverse voltage	V_{RRM}		600	V
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, With heatsink, TI=120°C *	10	А
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On alumina substrate, Ta=25°C *	2.2	А
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C *	2.1	А
Surge forward current	I _{FSM}	50Hz sine wave, Non-repetitive 1 cycle peak value, Tj=25°C	220	А
Surge forward current	I _{FSM1}	tp=1ms, sine wave, Non-repetitive, peak value, Tj=25°C	450	А

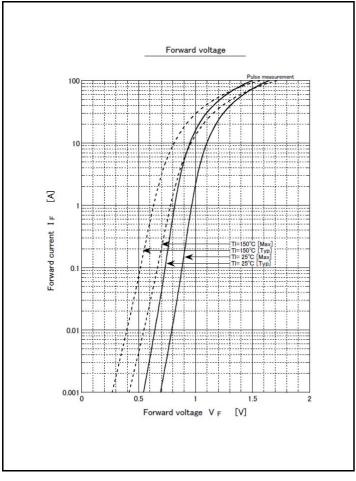
^{*} :See the original Specifications

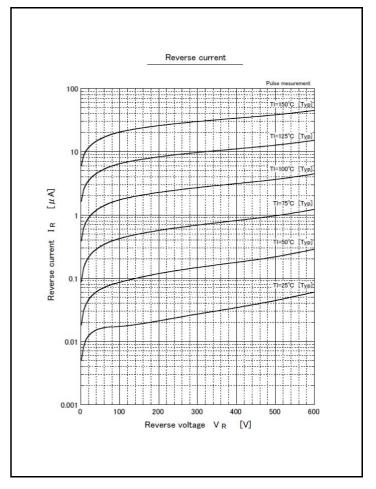
Electrical Characteristics (unless otherwise specified : Tc=25°C)

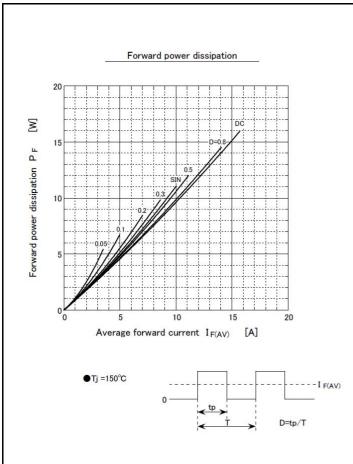
Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	Oint
Forward voltage	V _F	IF=10A, Pulse measurement			1.1	V
Reverse current	I _R	VR=600V, Pulse measurement			10	μΑ
Electro static dischange Capability	V _{ESD}	C=330pF, R=330Ω, Polarity±, Aerial discharge		25		kV
Thermal resistance	Rth(j-l)	Junction to lead, With heatsink *			2.7	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On alumina substrate *			60	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate *			65	°C/W

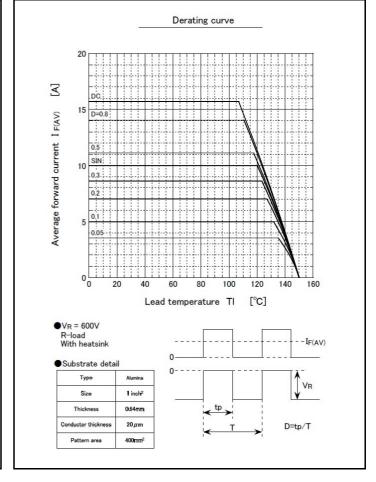
^{* :}See the original Specifications

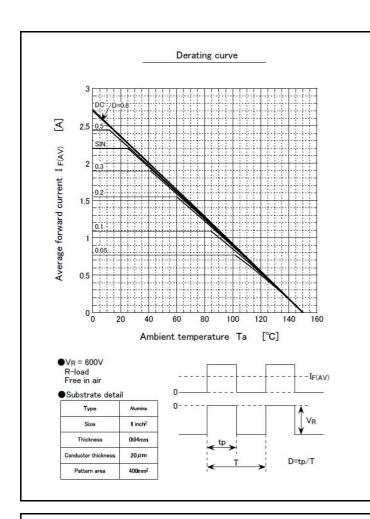
CHARACTERISTIC DIAGRAMS

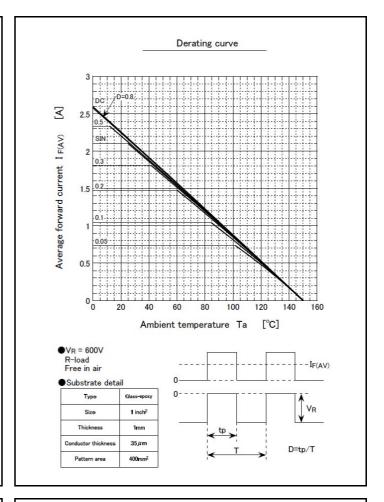


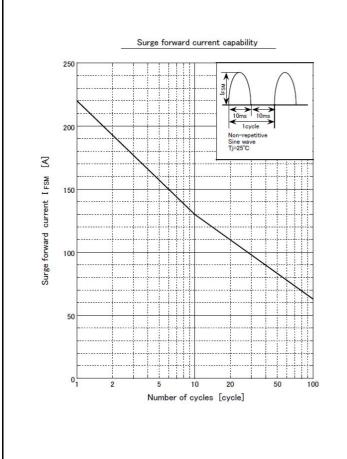


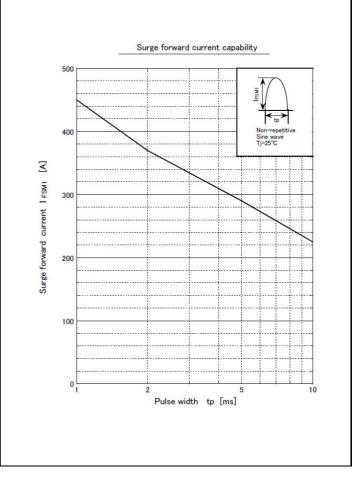


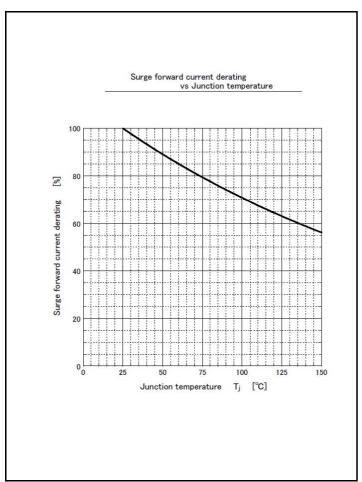


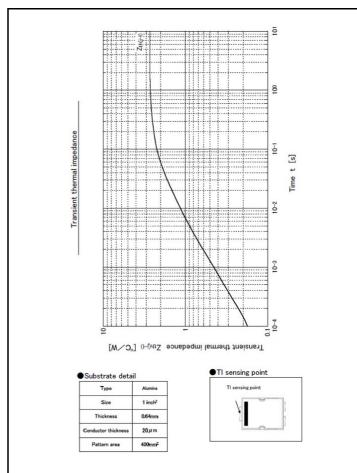


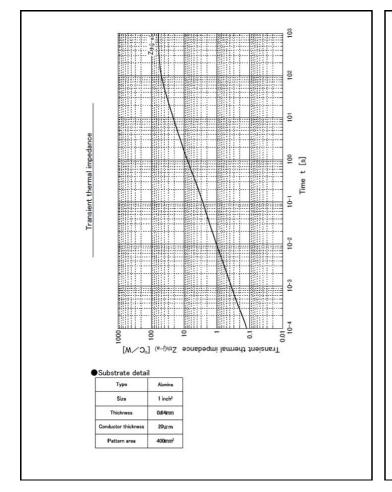


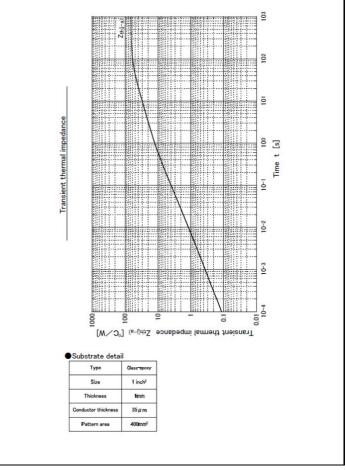








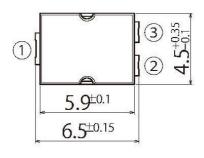


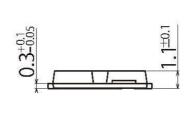


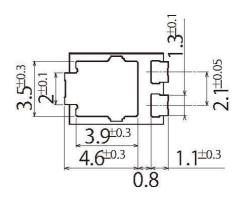
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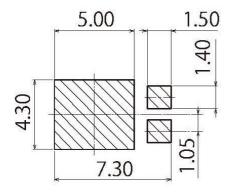
G4

JEDEC Code	TO-277A similar			
JEITA Code	_			
House Name	FY			









Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

Notes

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